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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/677,182	10/02/2003	Jee-Soo Mok	LEPA121687	8329
26389	7590 08/23/2006		EXAMINER	
CHRISTENSEN, O'CONNOR, JOHNSON, KINDNESS, PLLC			AHMED, SHAMIM .	
1420 FIFTH SUITE 2800	<del>-</del> -		ART UNIT	PAPER NUMBER
SEATTLE,	WA 98101-2347		1765	

DATE MAILED: 08/23/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	$\overline{}$
	10/677,182	MOK ET AL.	
Office Action Summary	Examiner	Art Unit	
	Shamim Ahmed	1765	
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the	correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D.  - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNICATIO 136(a). In no event, however, may a reply be ti will apply and will expire SIX (6) MONTHS from e, cause the application to become ABANDON	N. mely filed the mailing date of this communication. ED (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on 12 J	lune 2006.		
,	s action is non-final.		
3) Since this application is in condition for allowed closed in accordance with the practice under	ance except for formal matters, pr		
Disposition of Claims			
4) Claim(s) 1-21 is/are pending in the application 4a) Of the above claim(s) is/are withdra 5) Claim(s) is/are allowed. 6) Claim(s) 1-21 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or	wn from consideration.		
Application Papers			
9) The specification is objected to by the Examin	er.		
10)☐ The drawing(s) filed on is/are: a)☐ acc	cepted or b) objected to by the	Examiner.	
Applicant may not request that any objection to the	drawing(s) be held in abeyance. Se	e 37 CFR 1.85(a).	
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the E			
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Burea	ts have been received. ts have been received in Applica prity documents have been receiv	tion No	
* See the attached detailed Office action for a lis	t of the certified copies not receiv	ed.	
Attachment(s)			
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Discourse Statement(s) (PTO-1449 or PTO/SB/08)		y (PTO-413) Pate Patent Application (PTO-152)	
Paper No(s)/Mail Date	6)		

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#### **DETAILED ACTION**

### Response to Arguments

1. Applicant's arguments filed 6/12/06 have been fully considered but they are not persuasive. Applicant's arguments as to the point that cited references do not teach "irradiating a laser beam to the laminated thermosetting film according to a solder resist" is not commensurate with the claim because the claim is limited to irradiating the laser beam to the thermosetting resin film according to solder resist mask pattern that has been previously designed not previously formed.

- 2. As to Urasaki et al, applicants argue that the reference applies a laser bema to the thermosetting resin film to form via holes not for the purpose of selectively removing the film.
- 3. In response, examiner states that the argument is not persuasive because Urasaki et al' teaching of forming via holes by irradiating laser beam to the thermosetting resin film is nothing but selectively removing the film with the laser beam irradiation.

Therefore, the rejection of the previous office along with modification, which modification is due to the amendment to the claims as below:

## Claim Rejections - 35 USC § 103

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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- 5. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 6. Claims 1-12 and 13-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kamayachi et al (4,943,516) in view of Applicant's admitted prior art (AAPA).

Kamayachi et al disclose a process of forming a solder resist pattern on a printed circuit board (col.1, lines 7-20), wherein the process including the steps of:

- ➤ Laminating or depositing a thermosetting resin on a printed circuit board (PCB) having circuits formed thereon, wherein the resin can be in a wet or dry state (semi-cured);
- The coating is then directly exposed to a laser beam through a photomask having a prescribed pattern;
- Post-curing the developed thermosetting resin pattern to form solder resist pattern (col.15, line 67-col.16, line 31).

Kamayachi et al remain silent about the pre-treating the printed circuit board before lamination step.

However, Applicant's admitted prior art (AAPA, herein after) teach pretreating such as scrubbing process is carried out on both sides of the substrate to improve the adhesion between the photo solder resist (PSR) and the substrate (see specification page 6, lines 8-10).

Therefore, it would have been obvious to one of ordinary skilled in the art at the time of claimed invention to combine AAPA's teaching into Kamayachi et al's process for increasing bonding capability between the circuit board substrate and polymeric solder resist material as taught by AAPA.

7. Claims 1-12 and 13-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Urasaki et al (5,879,568) in view of Applicant's admitted prior art (AAPA).

Urasaki et al wherein the process including the steps of:

- depositing a thermosetting resin on a printed circuit board (PCB) having circuits formed thereon, wherein the resin can be cured by heating (col.2, lines 61-col.3, line 2).
- ➤ the resin layer is then selectively irradiating with a laser beam in order to form prescribed solder resist pattern, wherein the types of laser includes carbon dioxide laser, YAG laser or excimer laser (col.7, lines 50-58 and col.9, lines 49-col.10, lines 57).

Urasaki et al remain silent about the pre-treating the printed circuit board before lamination step.

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However, Applicant's admitted prior art (AAPA, herein after) teach pretreating such as scrubbing process is carried out on both sides of the substrate to improve the adhesion between the photo solder resist (PSR) and the substrate (see specification page 6, lines 8-10).

Therefore, it would have been obvious to one of ordinary skilled in the art at the time of claimed invention to combine AAPA's teaching into Urasaki et al's process for increasing bonding capability between the circuit board substrate and polymeric solder resist material as taught by AAPA.

#### Conclusion

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Shamim Ahmed whose telephone number is (571) 272-1457. The examiner can normally be reached on M-Thu (7:00-5:30) Every Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine G. Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Shamim Ahmed Primary Examiner Art Unit 1765

SA August 19, 2006